



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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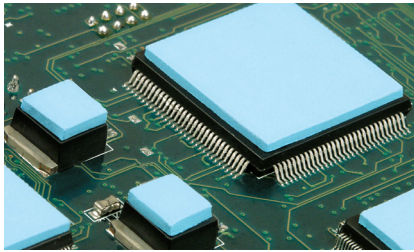


Gap Pad® 3000S30

Thermally Conductive, Reinforced, Soft "S-Class" Gap Filling Material

Features and Benefits

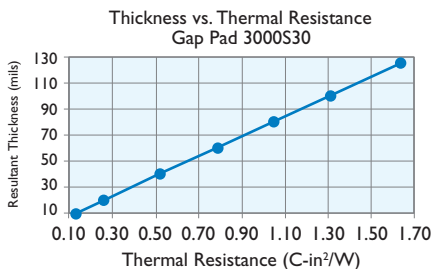
- Thermal conductivity: 3.0 W/m-K
- Low "S-Class" thermal resistance at very low pressures
- Highly conformable, "S-Class" softness
- Designed for low-stress applications
- Fiberglass reinforced for puncture, shear and tear resistance



Gap Pad 3000S30 is a soft gap filling material rated at a thermal conductivity of 3 W/m-K. The material offers exceptional thermal performance at low pressures due to an all-new 3 W/m-K filler package and low-modulus resin formulation. It is reinforced to enhance material handling, puncture, shear and tear resistance. It is well suited for high performance, low-stress applications that typically use fixed standoff or clip mounting. Gap Pad 3000S30 maintains a conformable yet elastic nature that allows for excellent interfacing and wet-out characteristics, even to surfaces with high roughness and/or topography.

Gap Pad 3000S30 is offered with natural inherent tack on both sides of the material, eliminating the need for thermally-impeding adhesive layers. The material's natural inherent tack allows for stick-in-place characteristics during assembly. Gap Pad 3000S30 is supplied with protective liners on both sides. The top side has reduced tack for ease of handling.

Note: Resultant thickness is defined as the final gap thickness of the application.



TYPICAL PROPERTIES OF GAP PAD 3000S30			
PROPERTY	IMPERIAL VALUE	METRIC VALUE	TEST METHOD
Color	Light Blue	Light Blue	Visual
Reinforcement Carrier	Fiberglass	Fiberglass	—
Thickness (inch) / (mm)	0.010 to 0.125	0.254 to 3.175	ASTM D374
Inherent Surface Tack (1 side)	2	2	—
Density (Bulk Rubber) (g/cc)	3.2	3.2	ASTM D792
Heat Capacity (J/g-K)	1.0	1.0	ASTM E1269
Hardness (Bulk Rubber) (Shore 00) (1)	30	30	ASTM D2240
Young's Modulus (psi) / (kPa) (2)	26	180	ASTM D575
Continuous Use Temp (°F) / (°C)	-76 to 392	-60 to 200	—
ELECTRICAL			
Dielectric Breakdown Voltage (Vac)	>3000	>3000	ASTM D149
Dielectric Constant (1000 Hz)	7.0	7.0	ASTM D150
Volume Resistivity (Ohm-meter)	10 ⁹	10 ⁹	ASTM D257
Flame Rating	V-O	V-O	UL 94
THERMAL			
Thermal Conductivity (W/m-K)	3.0	3.0	ASTM D5470
THERMAL PERFORMANCE vs. STRAIN			
	Deflection (% strain)		
	10	20	30
Thermal Impedance (°C-in ² /W) 0.040" (3)	0.66	0.60	0.54

1) Thirty second delay value Shore 00 hardness scale. 2) Young's Modulus, calculated using 0.01 in/min. step rate of strain with a sample size of 0.79 inch³. 3) The ASTM D5470 test fixture was used. The recorded value includes interfacial thermal resistance. These values are provided for reference only. Actual application performance is directly related to the surface roughness, flatness and pressure applied.

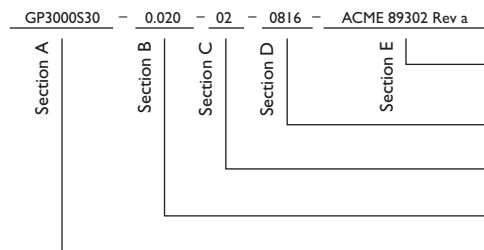
Typical Applications:

- Processors
- Server S-RAMs
- Mass storage drives
- Wireline / wireless communications hardware
- Notebook computers
- BGA packages
- Power conversion

Configurations Available:

- Sheet form and die-cut parts available

Building a Part Number



Standard Options

- ◀ example
- NA = Selected standard option. If not selecting a standard option, insert company name, drawing number, and revision level.
- 0816 = Standard sheet size 8" x 16", or
00 = custom configuration
- 02 = Natural tack, both sides
- Standard thicknesses available: 0.010", 0.015", 0.020", 0.040", 0.060", 0.080", 0.100", 0.125"
- GP3000S30 = Gap Pad 3000S30 Material

Note: To build a part number, visit our website at www.bergquistcompany.com.



www.bergquistcompany.com

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